Time Stamp	2005/03/23 14:36	2005/03/23 14:35	2005/03/23 15:23	2005/03/23 15:23	2005/03/23 14:36	2005/03/23 14:37	2005/03/23 15:23
Plurals Ti	ON 56	ON 20	ON 2	NO NO	NO O	N O	ON 5
Default	A N	OR R	S.	A R	A R	NO N	R
DBs	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT;
Search Query	(nano\$1probe (nano adj probe)) with ((substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) with silicon)	11 and @ad<"20030922"	(nano\$1probe (nano adj probe)) with (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)	i3 and @ad<"20030922"	14 and silicon	I5 and (project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment)	(nano\$1probe (nano adj probe)) same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)
Hits	7	2	42	35	73	m	9/
Ref	± IJ	7	<b>n</b>	4	<b>L</b> S	77	116

117	99	l16 and @ad<"20030922"		S.	NO	2005/03/23 15:23
			DERWENT; IBM_TDB	•		
170	7	7   117 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment))	US-PGPUB; USPAT; EPO; JPO;	OR	NO	2005/03/23 15:29
			IBM_TDB			
[2]	m	3 I20 and (conduct\$5 near2 (wir\$3 cord\$3 cabl\$3 line link channel connect\$5 lead\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	A S	NO	2005/03/23 15:27